

IN THE CLAIMS:

Please amend the claims as follows:

1. (Twice amended) An interposer [for use in a semiconductor device package], comprising:
a substrate element; and
a slot formed through said substrate element, said slot including a first end configured to extend beyond an outer periphery of a semiconductor die upon assembly of the interposer with the semiconductor die and a second end including a laterally recessed area formed in only a portion thereof.
4. (Amended) The interposer of claim 1, wherein said laterally recessed area is positioned [to be aligned] for alignment laterally adjacent to a bond pad of [a] the semiconductor die upon positioning the interposer over the semiconductor die, so as to be located laterally over a portion of an active surface of the semiconductor die located between the bond pad and an outer periphery of the semiconductor die.
18. (Twice amended) A semiconductor device assembly, comprising:
a semiconductor die with a plurality of bond pads on an active surface thereof, at least one bond pad of said plurality of bond pads being located adjacent an outer periphery of said semiconductor die; and
an interposer positionable over said semiconductor die, said interposer including at least one elongate slot formed therethrough, said at least one elongate slot including an end with a laterally recessed area formed in a portion thereof, said laterally recessed area, upon positioning said interposer over said semiconductor die, exposing said at least one bond pad and at least a portion of said active surface located between said at least one bond pad and said outer periphery of said semiconductor die.

23. (Amended) The semiconductor device assembly of claim 18, wherein said interposer is part of a strip comprising a plurality of physically connected interposers, each interposer of said plurality being configured [to be assembled] for assembly with a corresponding semiconductor die.